

Bill of Materials

TI DESIGNS
12 Gbps SAS-3 Link Extender
TIDA-00425

Item	Qty	Reference	Value	Part Description	Manufacturer	Manufacturer Part Number	Alternate Part	PCB Footprint	Note
1	37	C1,C2,C3,C4,C5,C6,C7,	0.10 uF	CAP CERAMIC 6.3V X5R	TDK Corporation	C0603X5R0J104M030BC	445-4711-1-ND	0201	
		C8,C9,C10,C11,C12,C13,							
		C14,C15,C16,C17,C18,							
		C19,C20,C21,C22,C23,							
		C24,C25,C26,C27,C28,							
		C29,C30,C31,C32,C33,							
2	1	C34	10 uF	CAP CERAMIC 6.3V X5R 10%	TDK Corporation	C2012X5R0J106M125AB	445-1363-1-ND	0805	
3	1	D1		LED GREEN 0.2MM 6MCD	Lite-On Inc.	LTST-C190GKT	160-1183-1-ND	0603	
4	2	J1,J2		MINISAS HD 1X1 REC	TE Connectivity	2149027-1	A104065-ND		
5	3	J3,J35,J36		TERM QF .052" DIAMETER	Keystone Electronics	1287-ST	1287-STK-ND		.250" STURDY MT
	15	J4,J6,J7,J8,J9,J10,J11,		CONN HEADER 3 POSITION	Molex Connector Corp	22284033	WM50016-03-ND		.100 VERT GOLD
		J18,J19,J21,J23,J24,							
6		J28,J31,J33							
	14	J12,J13,J14,J15,J16,J17,		CONN HEADER 2 POSITION	Molex Connector Corp	22284033	WM50016-02-ND		.100 VERT GOLD
		J22,J25,J26,J27,J29,J30,							
7		J32,J34							
8	1	J38		CONN HEADER 4 POSITION	Molex Connector Corp	22284033	WM50016-04-ND		.100 VERT GOLD
	32	R1,R2,R3,R4,R5,R6,R13,							
		R14,R15,R16,R17,R18,							
		R21,R22,R23,R24,R26,							
		R27,R28,R30,R32,R33,							
		R34,R35,R37,R40,R42,							
9		R43,R45,R46,R48,R49	1.00K	RES 1/10W 1%	Panasonic	ERJ-2RKF1001X	P1.00KLCT-ND	0402	
	12	R7,R8,R9,R10,R11,R12,							
10		R25,R29,R31,R41,R44,R47	20.0K	RES 1/10W 1%	Panasonic	ERJ-2RKF2002X	P20.0KLCT-ND	0402	
11	1	R19	220	RES 1/10W 1%	Panasonic	ERJ-2RKF2200X	P220LCT-ND	0402	
12	1	U1			Texas Instruments	DS125BR401ANJY		WQFN54	EQUALIZER
13	1	U2		SOCKET IC 8POS .3"	3M	4808-3004-CP	3M5473-ND		
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